

ABSTRACT

A method for manufacturing electronic apparatus includes: a step (A) of preparing a structure (100) provided with an adhesive film (50) and one or two or more electronic components (70) affixed to an adhesive surface of the adhesive film (50); a step (B) of disposing the structure (100) in the electronic component testing apparatus (200) such that the electronic component (70) is positioned over an electronic component installation region (85) of a sample stand (80) of the electronic component testing apparatus (200) with the adhesive film (50) interposed between the electronic component (70) and the electronic component installation region (85), the electronic component testing apparatus (200) being provided with the sample stand (80) including the electronic component installation region (85) and a probe card (90) that is provided at a position facing the sample stand (80) and includes a probe terminal (95); a step (C) of evaluating the properties of the electronic component (70) in a state of being affixed to the adhesive film (50) with the probe terminal (95) being in contact with a terminal (75) of the electronic component (70); and a step (D) of picking up the electronic component (70) from the adhesive film (50) after the step (C). In addition, the sample stand (80) is provided with a first vacuum suction unit (210) in a region (89) on an outer peripheral side which is different from the electronic component installation region (85), the first vacuum suction unit (210) vacuum-sucking the adhesive film (50), and at least in the step (C), the first vacuum suction unit (210) vacuum-sucks a region (58) of the adhesive film (50) to which no electronic

component (70) is affixed.